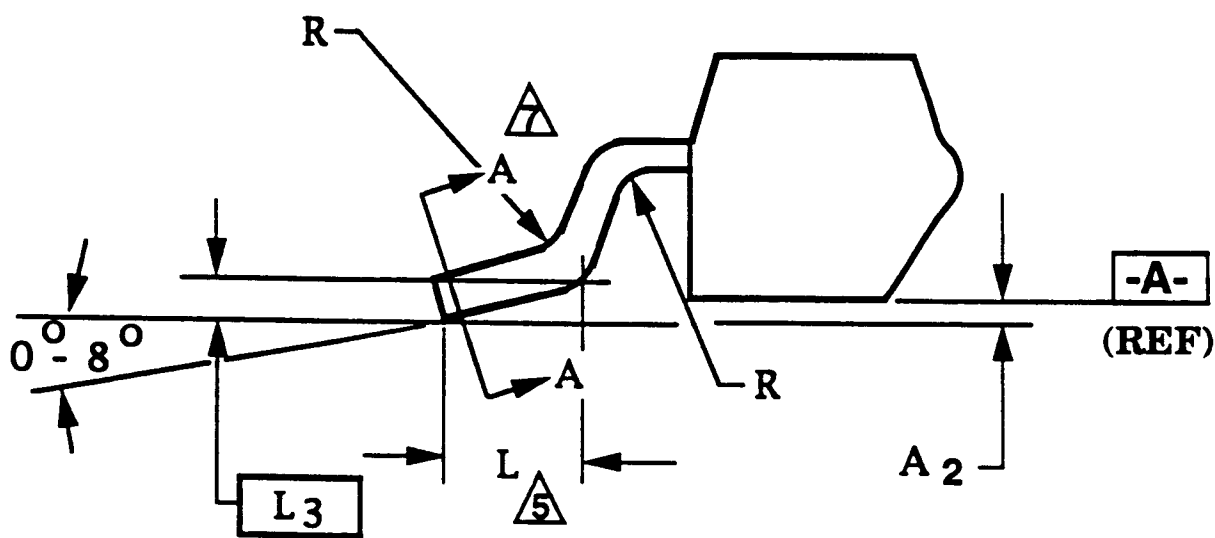
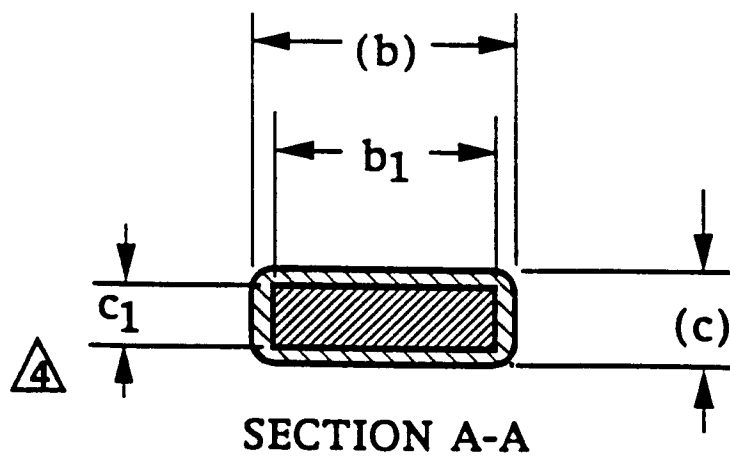


**BACK VIEW B - B**

THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY, CHANGES ARE LIKELY TO OCCUR.

<b>JEDEC</b> <b>SOLID STATE PRODUCT</b> <b>OUTLINES</b>	<b>TITLE: R-PSFM-G2</b> <b>HEADER FAMILY</b> <b>SURFACE MOUNTED</b> <b>(PERIPHERAL TERMINALS)</b>	<b>ISSUE</b> <b>A</b>	<b>DATE:</b> <b>6-95</b>	<b>TO -268</b>	<b>SHEET</b> <b>1</b> <b>OF</b> <b>3</b>
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**NOTES:**

1. REFER TO APPLICABLE SYMBOL LIST.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
3. TAB CONTOUR OPTIONAL WITHIN DIMENSION E & L<sub>2</sub>.
4. DIMENSIONS b<sub>1</sub> AND c<sub>1</sub> APPLY TO BASE METAL ONLY. DIMENSIONS b & c APPLY TO PLATED LEADS.
5. L IS THE TERMINAL LENGTH FOR SOLDERING.
6. D<sub>1</sub> & E<sub>1</sub> ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERM 4.
7. SECTION A-A DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .13 TO .25 MILLIMETERS FROM THE LEAD TIP.
8. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .13 MILLIMETERS PER SIDE.
9. ALL DIMENSIONS IN MILLIMETER.

SYMBOL	VARIATIONS					
	AA					
	MIN	NOM	MAX	NOTES		
A	4.90	5.00	5.10			
A1	2.70	2.80	2.90			
A2	.02	.10	.25			
b	1.15	-	1.45	4,7		
b1	1.15	1.25	1.40	4,7		
b2	1.90	2.00	2.10			
c	.40	-	.65	4,7		
c1	.40	.50	.60	4,7		
c2	1.45	1.50	1.60			
D	13.80	13.90	14.00	8		
D1	12.40	12.55	12.70	6		
E	15.85	15.95	16.05			
E1	13.30	13.45	13.60	6		
e		5.45 BSC				
H	18.70	18.90	19.10			
L	2.40	2.55	2.70	5		
L1	1.20	1.30	1.40			
L2	1.00	1.10	1.15	3		
L3		.25 BSC				
R	1.00	1.50	2.00			
NOTE	1, 2, 9					
REF.	10-352					
ISSUE						
JEDEC SOLID STATE PRODUCT OUTLINES		TITLE: R-PSFM-G2 HEADER FAMILY SURFACE MOUNTED (PERIPHERAL TERMINALS)	ISSUE A	DATE 6-95	TO-268	SHEET 3 OF 3